

IEEE 802.3 Ethernet Working Group

Membership list

as of 15 November 2019

(193)

Scope of the Working Group

The IEEE 802.3 Working Group is chartered to maintain and revise the Ethernet standard, develop new Ethernet standards in a reasonable time frame, forward these standards to ISO/IEC JTC1 SC6, and maintain liaisons with other groups within the IEEE 802 LAN/MAN Standards Committee and other relevant standards development organizations.

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